

PDTC123Y series

NPN resistor-equipped transistors; R1 = 2.2 kΩ, R2 = 10 kΩ

Rev. 03 — 24 March 2005

Product data sheet

1. Product profile

1.1 General description

NPN Resistor-Equipped Transistors (RET) family.

Table 1: Product overview

Type number	Package			PNP complement
	Philips	JEITA	JEDEC	
PDTC123YE	SOT416	SC-75	-	PDTA123YE
PDTC123YK	SOT346	SC-59A	TO-236	PDTA123YK
PDTC123YM	SOT883	SC-101	-	PDTA123YM
PDTC123YS ^[1]	SOT54	SC-43A	TO-92	PDTA123YS
PDTC123YT	SOT23	-	TO-236AB	PDTA123YT
PDTC123YU	SOT323	SC-70	-	PDTA123YU

[1] Also available in SOT54A and SOT54 variant packages (see [Section 2](#)).

1.2 Features

- Built-in bias resistors
- Simplifies circuit design
- Reduces component count
- Reduces pick and place costs

1.3 Applications

- General-purpose switching and amplification
- Inverter and interface circuits
- Circuit drivers

1.4 Quick reference data

Table 2: Quick reference data

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{CEO}	collector-emitter voltage	open base	-	-	50	V
I _O	output current (DC)		-	-	100	mA
R1	bias resistor 1 (input)		1.54	2.2	2.86	kΩ
R2/R1	bias resistor ratio		3.6	4.5	5.5	

PHILIPS

2. Pinning information

Table 3: Pinning

Pin	Description	Simplified outline	Symbol
SOT54			
1	input (base)		
2	output (collector)		
3	GND (emitter)		
SOT54A			
1	input (base)		
2	output (collector)		
3	GND (emitter)		
SOT54 variant			
1	input (base)		
2	output (collector)		
3	GND (emitter)		
SOT23; SOT323; SOT346; SOT416			
1	input (base)		
2	GND (emitter)		
3	output (collector)		
SOT883			
1	input (base)		
2	GND (emitter)		
3	output (collector)		



3. Ordering information

Table 4: Ordering information

Type number	Package			Version
	Name	Description		
PDTC123YE	SC-75	plastic surface mounted package; 3 leads		SOT416
PDTC123YK	SC-59A	plastic surface mounted package; 3 leads		SOT346
PDTC123YM	SC-101	leadless ultra small plastic package; 3 solder lands; body 1.0 × 0.6 × 0.5 mm		SOT883
PDTC123YS [1]	SC-43A	plastic single-ended leaded (through hole) package; 3 leads		SOT54
PDTC123YT	-	plastic surface mounted package; 3 leads		SOT23
PDTC123YU	SC-70	plastic surface mounted package; 3 leads		SOT323

[1] Also available in SOT54A and SOT54 variant packages (see [Section 2](#) and [Section 9](#)).

4. Marking

Table 5: Marking codes

Type number	Marking code [1]
PDTC123YE	19
PDTC123YK	31
PDTC123YM	G7
PDTC123YS	TC123Y
PDTC123YT	*AL
PDTC123YU	*19

[1] * = -: made in Hong Kong
 * = p: made in Hong Kong
 * = t: made in Malaysia
 * = W: made in China

5. Limiting values

Table 6: Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions	Min	Max	Unit
V _{CBO}	collector-base voltage	open emitter	-	50	V
V _{CEO}	collector-emitter voltage	open base	-	50	V
V _{EBO}	emitter-base voltage	open collector	-	5	V
V _I	input voltage				
	positive		-	+12	V
	negative		-	-5	V
I _O	output current (DC)		-	100	mA
I _{CM}	peak collector current	single pulse; t _p ≤ 1ms	-	100	mA
P _{tot}	total power dissipation	T _{amb} ≤ 25 °C			
	SOT416	[1]	-	150	mW
	SOT346	[1]	-	250	mW
	SOT883	[2][3]	-	250	mW
	SOT54	[1]	-	500	mW
	SOT23	[1]	-	250	mW
	SOT323	[1]	-	200	mW
T _{stg}	storage temperature		-65	+150	°C
T _j	junction temperature		-	150	°C
T _{amb}	ambient temperature		-65	+150	°C

[1] Device mounted on an FR4 Printed-Circuit Board (PCB), single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

[3] Device mounted on an FR4 PCB with 60 µm copper strip line, standard footprint.

6. Thermal characteristics

Table 7: Thermal characteristics

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
R _{th(j-a)}	thermal resistance from junction to ambient	in free air				
	SOT416	[1]	-	-	833	K/W
	SOT346	[1]	-	-	500	K/W
	SOT883	[2][3]	-	-	500	K/W
	SOT54	[1]	-	-	250	K/W
	SOT23	[1]	-	-	500	K/W
	SOT323	[1]	-	-	625	K/W

[1] Device mounted on an FR4 PCB, single-sided copper, tin-plated and standard footprint.

[2] Reflow soldering is the only recommended soldering method.

[3] Device mounted on an FR4 PCB with 60 µm copper strip line, standard footprint.

7. Characteristics

Table 8: Characteristics $T_{amb} = 25^\circ\text{C}$ unless otherwise specified.

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
I _{CBO}	collector-base cut-off current	V _{CB} = 50 V; I _E = 0 A	-	-	100	nA
I _{CEO}	collector-emitter cut-off current	V _{CE} = 30 V; I _B = 0 A	-	-	1	μA
		V _{CE} = 30 V; I _B = 0 A; T _j = 150 °C	-	-	50	μA
I _{EBO}	emitter-base cut-off current	V _{EB} = 5 V; I _C = 0 A	-	-	700	μA
h _{FE}	DC current gain	V _{CE} = 5 V; I _C = 5 mA	35	-	-	
V _{CEsat}	collector-emitter saturation voltage	I _C = 10 mA; I _B = 0.5 mA	-	-	150	mV
V _{I(off)}	off-state input voltage	V _{CE} = 5 V; I _C = 100 μA	-	0.75	0.3	V
V _{I(on)}	on-state input voltage	V _{CE} = 300 mV; I _C = 20 mA	2.5	1.15	-	V
R1	bias resistor 1 (input)		1.54	2.2	2.86	kΩ
R2/R1	bias resistor ratio		3.6	4.5	5.5	
C _c	collector capacitance	V _{CB} = 10 V; I _E = i _e = 0 A; f = 1 MHz	-	-	2	pF

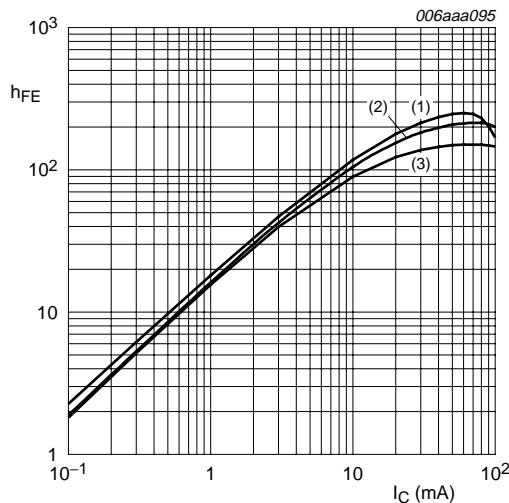


Fig 1. DC current gain as a function of collector current; typical values

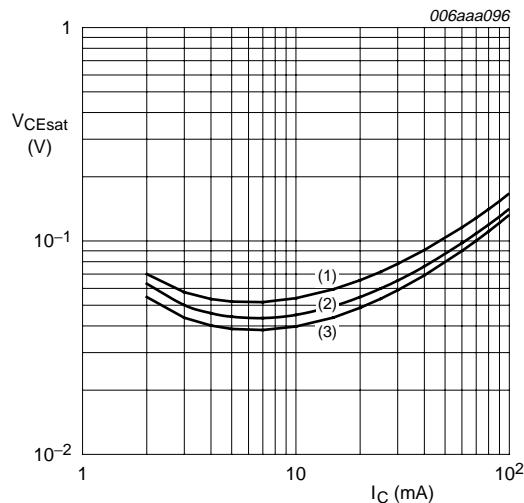


Fig 2. Collector-emitter saturation voltage as a function of collector current; typical values

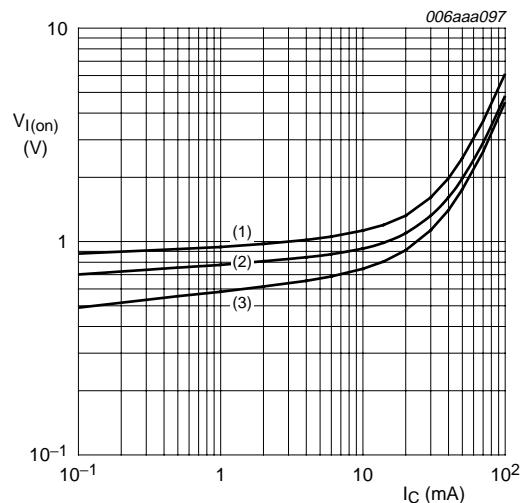


Fig 3. On-state input voltage as a function of collector current; typical values

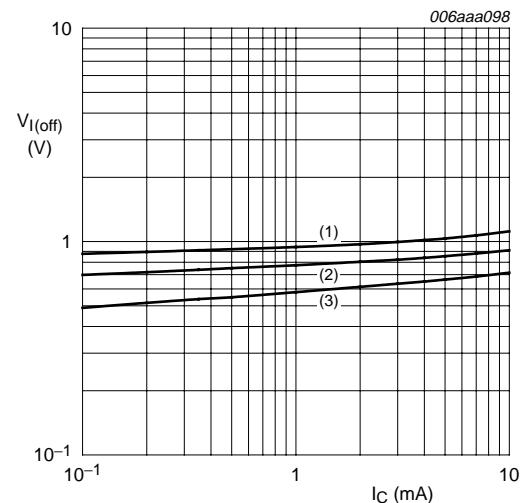


Fig 4. Off-state input voltage as a function of collector current; typical values

8. Package outline

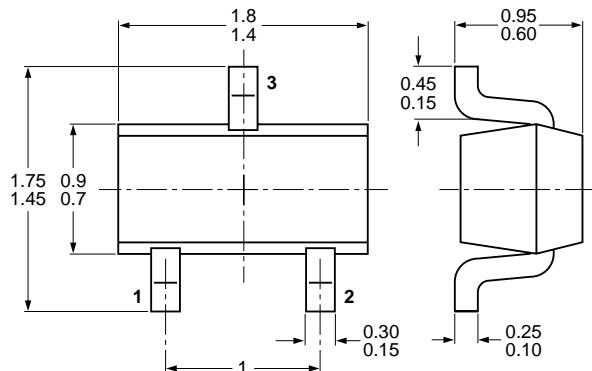


Fig 5. Package outline SOT416 (SC-75)

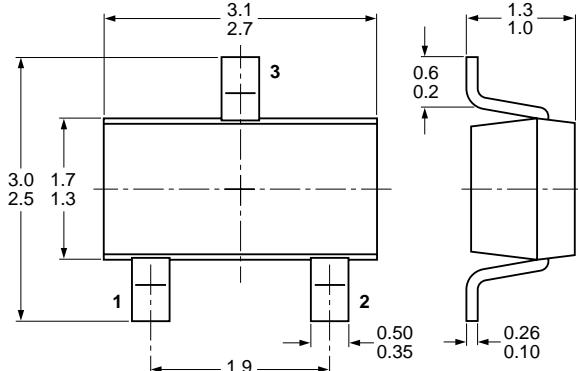


Fig 6. Package outline SOT346 (SC-59A/TO-236)

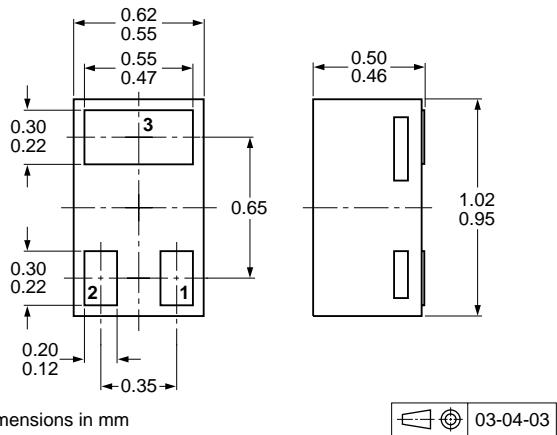


Fig 7. Package outline SOT883 (SC-101)

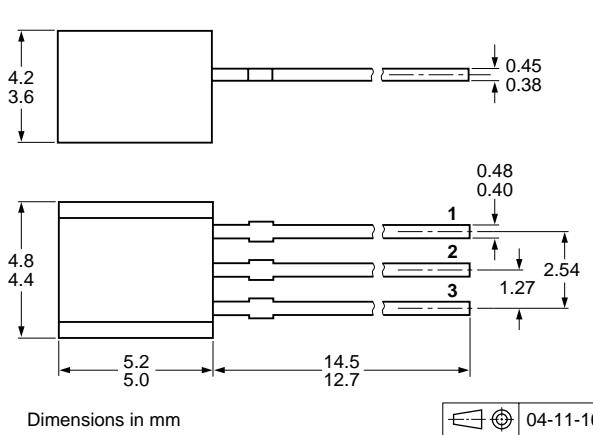


Fig 8. Package outline SOT54 (SC-43A/TO-92)

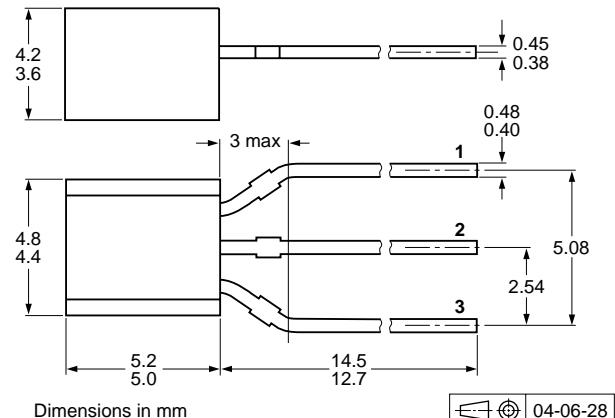


Fig 9. Package outline SOT54A

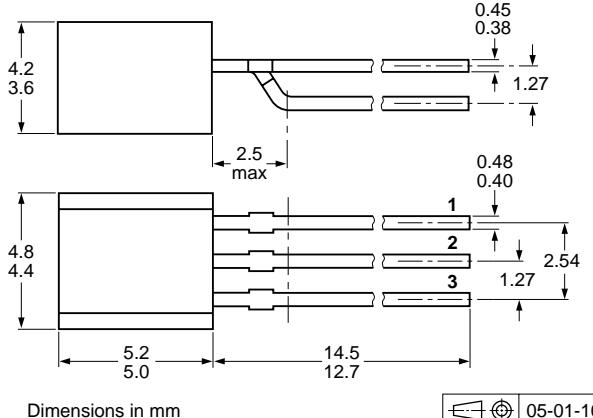
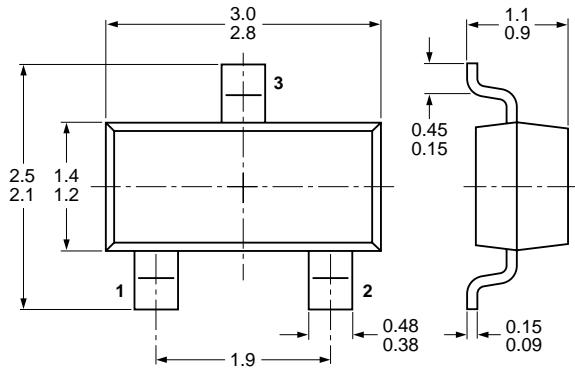


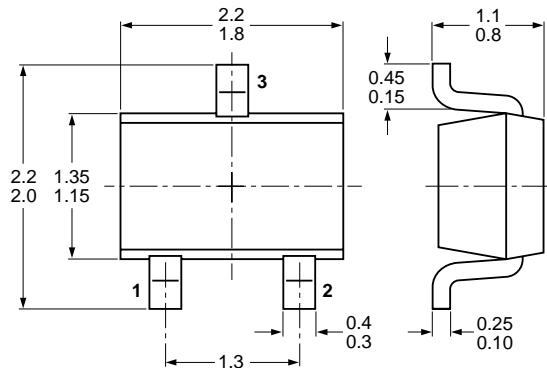
Fig 10. Package outline SOT54 variant



Dimensions in mm

04-11-04

Fig 11. Package outline SOT23 (TO-236AB)



Dimensions in mm

04-11-04

Fig 12. Package outline SOT323 (SC-70)

9. Packing information

Table 9: Packing methods

The indicated -xxx are the last three digits of the 12NC ordering code. [1]

Type number	Package	Description	Packing quantity		
			3000	5000	10000
PDTC123YE	SOT416	4 mm pitch, 8 mm tape and reel	-115	-	-135
PDTC123YK	SOT346	4 mm pitch, 8 mm tape and reel	-115	-	-135
PDTC123YM	SOT883	2 mm pitch, 8 mm tape and reel	-	-	-315
PDTC123YS	SOT54	bulk, straight leads	-	-412	-
	SOT54A	tape and reel, wide pitch	-	-	-116
		tape ammopack, wide pitch	-	-	-126
	SOT54 variant	bulk, delta pinning	-	-112	-
PDTC123YT	SOT23	4 mm pitch, 8 mm tape and reel	-215	-	-235
PDTC123YU	SOT323	4 mm pitch, 8 mm tape and reel	-115	-	-135

[1] For further information and the availability of packing methods, see [Section 14](#).



10. Revision history

Table 10: Revision history

Document ID	Release date	Data sheet status	Change notice	Doc. number	Supersedes
PDTC123Y_SER_3	20050324	Product data sheet	-	9397 750 14017	PDTC123YT_2
Modifications:	<ul style="list-style-type: none"> • The types PDTC123YE, PDTC123YK, PDTC123YM, PDTC123YS and PDTC123YU were added. • Table 1 "Product overview" added • Table 8 "Characteristics" $V_{i(on)}$ redefined to $V_{I(on)}$ on-state input voltage • Table 8 "Characteristics" $V_{i(off)}$ redefined to $V_{I(off)}$ off-state input voltage • Figure 1, 2, 3 and 4 added • Section 9 "Packing information" added 				
PDTC123YT_2	20040510	Objective data sheet	-	9397 750 13208	PDTC123YT_1
PDTC123YT_1	20040406	Objective data sheet	-	9397 750 12555	-



11. Data sheet status

Level	Data sheet status [1]	Product status [2][3]	Definition
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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[2] The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL <http://www.semiconductors.philips.com>.

[3] For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

12. Definitions

Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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